

## Medium Power AF Schottky Diode

- Forward current: 1 A
- Reverse voltage: 30 V
- Very low forward voltage (typ. 0.41V @ *I*<sub>F</sub> = 1A)
- For high efficiency DC/DC conversion, fast switching, protection and clamping applications
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



## **BAS 3010A-03W**

1	K	2	

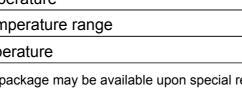
Туре	Package	Configuration	Marking
BAS3010A-03W	SOD323	single	4/ blue

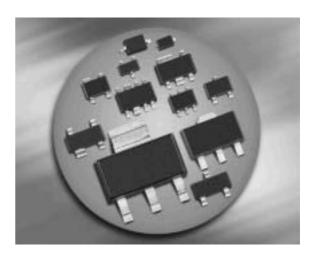
# **Maximum Ratings** at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage <sup>2)</sup>	V <sub>R</sub>	30	V
Forward current <sup>2)</sup>	I <sub>F</sub>	1	А
Average rectified forward current (50/60Hz, sinus)	) / <sub>FAV</sub>	1	
Repetitive peak forward current	/ <sub>FRM</sub>	3.5	
$(t_{\rm p} \le 1 {\rm ~ms},  D \le 0.5)$			
Non-repetitive peak surge forward current	/ <sub>FSM</sub>	10	
( <i>t</i> ≤ 10ms)			
Junction temperature	Ti	150	°C
Operating temperature range	T <sub>op</sub>	-65 125	
Storage temperature	T <sub>stg</sub>	-65 150	

<sup>1</sup>Pb-containing package may be available upon special request

<sup>2</sup>For  $T_A > 25^{\circ}$ C the derating of  $V_R$  and  $I_F$  has to be considered. Please refer to the attached curves.







#### **Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	R <sub>thJS</sub>	≤ 82	K/W

#### **Electrical Characteristics** at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Reverse current <sup>2)</sup>	I <sub>R</sub>				μA
$V_{R}$ = 5 V		-	5	25	
<i>V</i> <sub>R</sub> = 10 V		-	10	50	
<i>V</i> <sub>R</sub> = 30 V		-	40	200	
Forward voltage <sup>2)</sup>	V <sub>F</sub>				mV
<i>I</i> <sub>F</sub> = 1 mA		-	170	220	
/ <sub>F</sub> = 10 mA		-	220	270	
<i>I</i> <sub>F</sub> = 100 mA		-	290	340	
I <sub>F</sub> = 500 mA		-	350	410	
<i>I</i> <sub>F</sub> = 1 A		-	410	470	
AC Characteristics		·			
Diode capacitance	CT	-	28	35	pF
$V_{R} = 5 V, f = 1 MHz$					

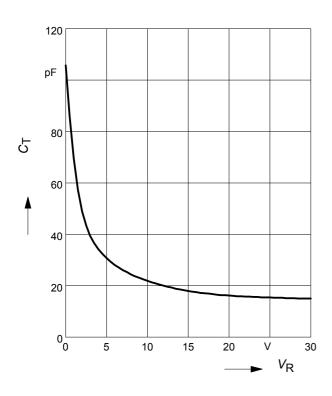
<sup>1</sup>For calculation of  $R_{\rm thJA}$  please refer to Application Note Thermal Resistance

<sup>2</sup>Pulsed test:  $t_{\rm p}$  = 300 µs; D = 0.01



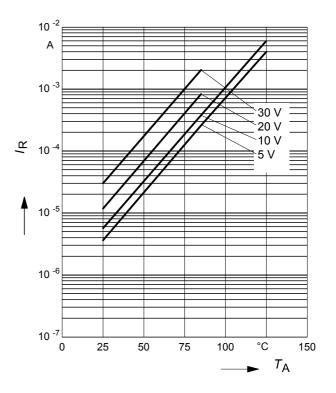
## **Diode capacitance** $C_T = f(V_R)$

f = 1 MHz



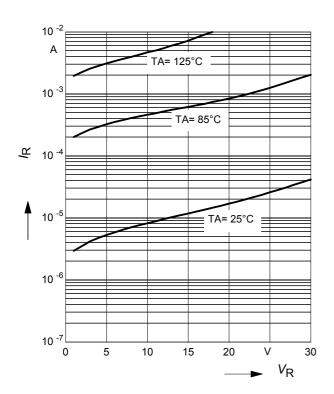
**Reverse current**  $I_{R} = f(T_{A})$ 

 $V_{\rm R}$  = Parameter



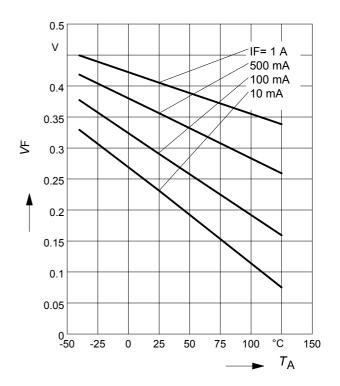
**Reverse current**  $I_{R} = f(V_{R})$ 

 $T_A$  = Parameter



Forward Voltage  $V_{\rm F} = f(T_{\rm A})$ 

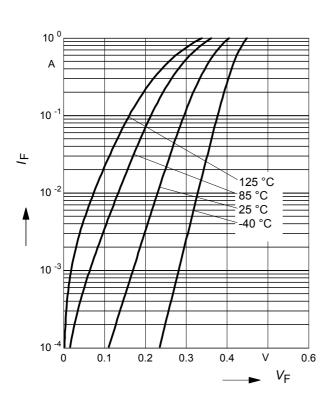
 $I_{\rm F}$  = Parameter





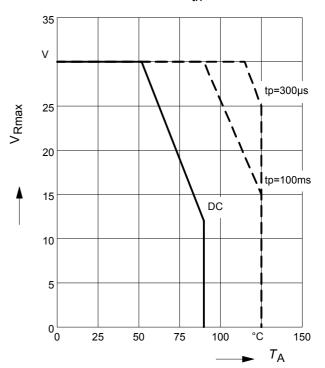
## Forward current $I_F = f(V_F)$

 $T_A$  = Parameter

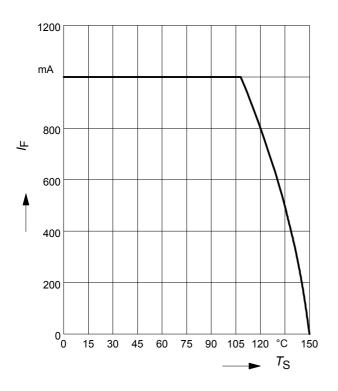


Permissible Reverse voltage  $V_{R} = f(T_{A})$ 

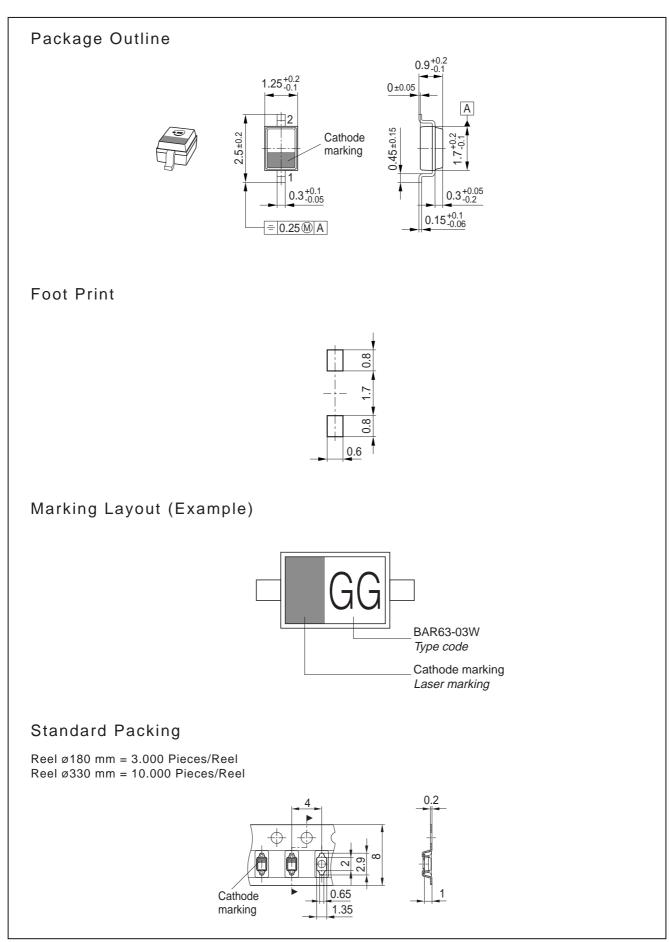
 $t_{\rm p}$  = Parameter, Duty cycle < 0.01 Device mounted on PCB with  $R_{\rm th}$  = 160 k/W



Forward current  $I_{\rm F}$  =  $f(T_{\rm S})$ 









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